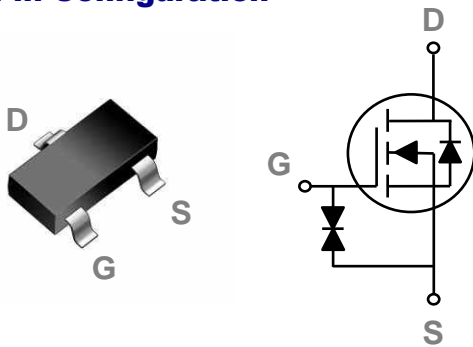


### General Description

These N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

### SOT523 Pin Configuration



BVDSS	RDSON	ID
30V	500mΩ	600mA

### Features

- 30V,600mA,  $R_{DS(ON)} = 500m\Omega @ V_{GS} = 4.5V$
- Improved  $dv/dt$  capability
- Fast switching
- Green Device Available
- Suit for 2.5V Gate Drive Applications

### Applications

- Notebook
- Load Switch
- Battery Protection
- Hand-held Instruments

### Absolute Maximum Ratings $T_c=25^\circ C$ unless otherwise noted

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	30	V
$V_{GS}$	Gate-Source Voltage	$\pm 12$	V
$I_D$	Drain Current – Continuous ( $T_c=25^\circ C$ )	600	mA
	Drain Current – Continuous ( $T_c=75^\circ C$ )	460	mA
$I_{DM}$	Drain Current – Pulsed <sup>1</sup>	2.4	A
$P_D$	Power Dissipation ( $T_c=25^\circ C$ )	310	mW
	Power Dissipation – Derate above $25^\circ C$	2.5	mW/ $^\circ C$
$T_{STG}$	Storage Temperature Range	-55 to 150	$^\circ C$
$T_J$	Operating Junction Temperature Range	-55 to 150	$^\circ C$

### Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction to ambient	---	400	$^\circ C/W$

**Electrical Characteristics (T<sub>J</sub>=25 °C, unless otherwise noted)**
**Off Characteristics**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>D</sub> =250μA	30	---	---	V
ΔBV <sub>DSS</sub> /ΔT <sub>J</sub>	BV <sub>DSS</sub> Temperature Coefficient	Reference to 25°C, I <sub>D</sub> =1mA	---	-0.03	---	V/°C
I <sub>DSS</sub>	Drain-Source Leakage Current	V <sub>DS</sub> =30V, V <sub>GS</sub> =0V, T <sub>J</sub> =25°C	---	---	1	μA
		V <sub>DS</sub> =24V, V <sub>GS</sub> =0V, T <sub>J</sub> =125°C	---	---	10	μA
I <sub>GSS</sub>	Gate-Source Leakage Current	V <sub>GS</sub> =±12V, V <sub>DS</sub> =0V	---	---	±20	μA

**On Characteristics**

R <sub>DS(ON)</sub>	Static Drain-Source On-Resistance	V <sub>GS</sub> =4.5V, I <sub>D</sub> =0.3A	---	420	500	mΩ
		V <sub>GS</sub> =2.5V, I <sub>D</sub> =0.2A	---	550	700	
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>GS</sub> =V <sub>DS</sub> , I <sub>D</sub> =250μA	0.5	0.8	1.2	V
ΔV <sub>GS(th)</sub>	V <sub>GS(th)</sub> Temperature Coefficient		---	-1.74	---	mV/°C
g <sub>fs</sub>	Forward Transconductance	V <sub>DS</sub> =4V, I <sub>D</sub> =0.3A	---	1	---	S

**Dynamic and switching Characteristics**

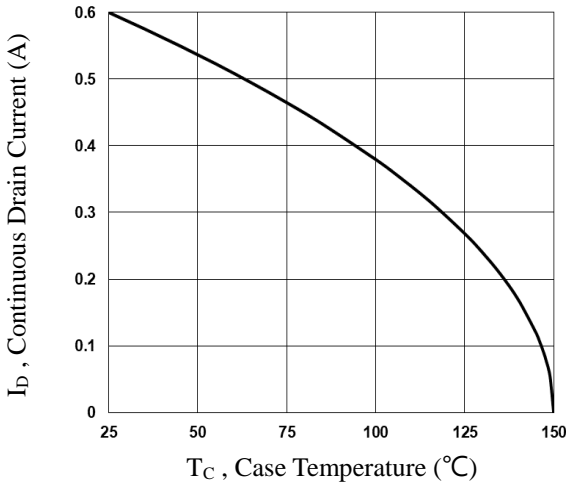
Q <sub>g</sub>	Total Gate Charge <sup>2, 3</sup>	V <sub>DS</sub> =15V, V <sub>GS</sub> =4.5V, I <sub>D</sub> =0.3A	---	2.6	5.2	nC
Q <sub>gs</sub>	Gate-Source Charge <sup>2, 3</sup>		---	0.9	1.8	
Q <sub>gd</sub>	Gate-Drain Charge <sup>2, 3</sup>		---	0.6	1.2	
T <sub>d(on)</sub>	Turn-On Delay Time <sup>2, 3</sup>	V <sub>DD</sub> =15V, V <sub>GS</sub> =4.5V, R <sub>G</sub> =10Ω I <sub>D</sub> =0.3A	---	5.5	11	ns
T <sub>r</sub>	Rise Time <sup>2, 3</sup>		---	4	8	
T <sub>d(off)</sub>	Turn-Off Delay Time <sup>2, 3</sup>		---	14.5	29	
T <sub>f</sub>	Fall Time <sup>2, 3</sup>		---	6.5	13	
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> =15V, V <sub>GS</sub> =0V, F=1MHz	---	72.9	146	pF
C <sub>oss</sub>	Output Capacitance		---	18.3	36.6	
C <sub>rss</sub>	Reverse Transfer Capacitance		---	7.4	14.8	

**Drain-Source Diode Characteristics and Maximum Ratings**

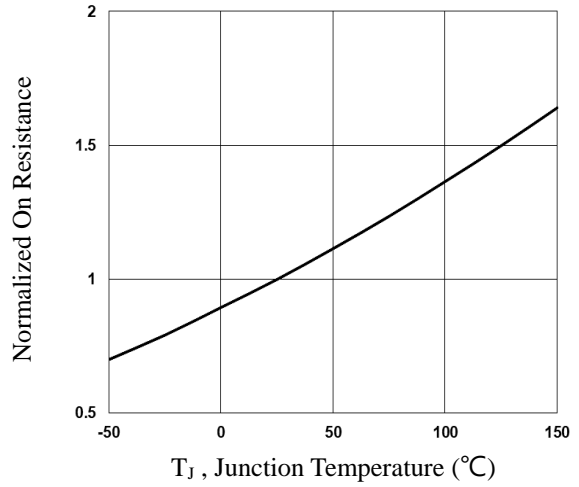
Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I <sub>S</sub>	Continuous Source Current	V <sub>G</sub> =V <sub>D</sub> =0V, Force Current	---	---	0.6	A
I <sub>SM</sub>	Pulsed Source Current		---	---	1.2	A
V <sub>SD</sub>	Diode Forward Voltage	V <sub>GS</sub> =0V, I <sub>S</sub> =0.3A, T <sub>J</sub> =25°C	---	---	1	V
T <sub>rr</sub>	Reverse Recovery Time	V <sub>GS</sub> =0V, I <sub>S</sub> =0.3A	---	13	---	ns
Q <sub>rr</sub>	Reverse Recovery Charge	di/dt=100A/μs T <sub>J</sub> =25°C	---	6	---	nC

Note :

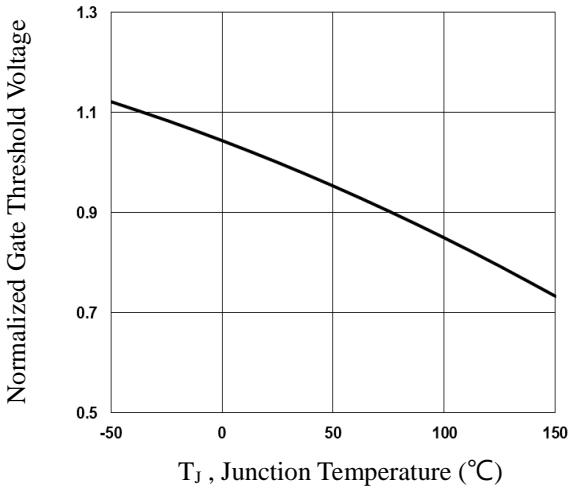
1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. The data tested by pulsed, pulse width ≤ 300us, duty cycle ≤ 2%.
3. Essentially independent of operating temperature.



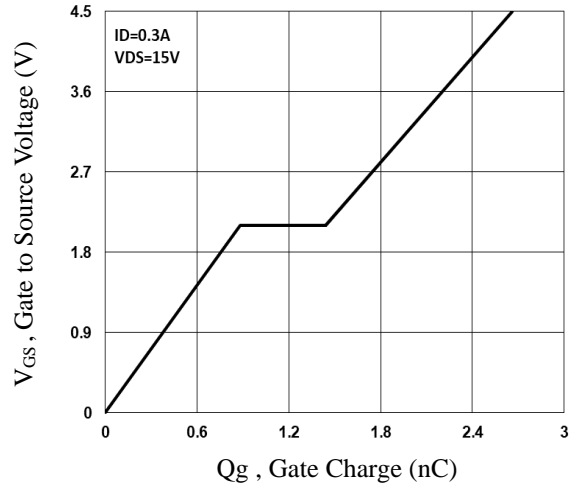
**Fig.1 Continuous Drain Current vs.  $T_c$**



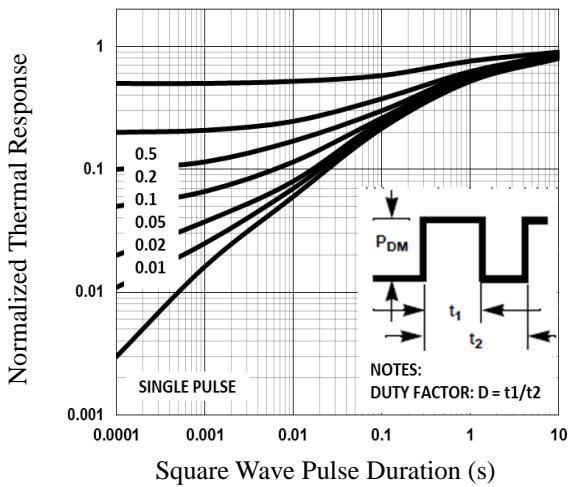
**Fig.2 Normalized  $R_{DS(on)}$  vs.  $T_j$**



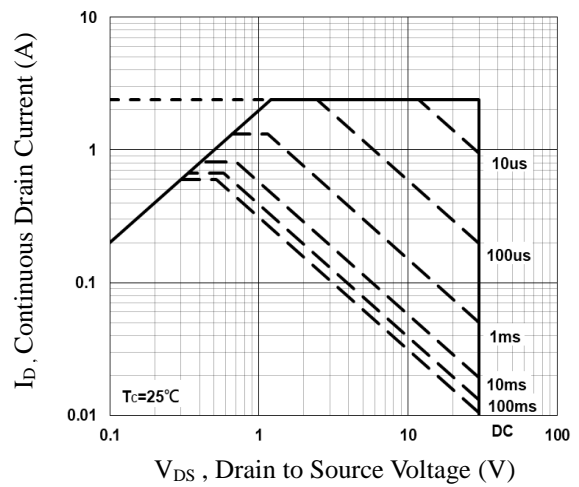
**Fig.3 Normalized  $V_{th}$  vs.  $T_j$**



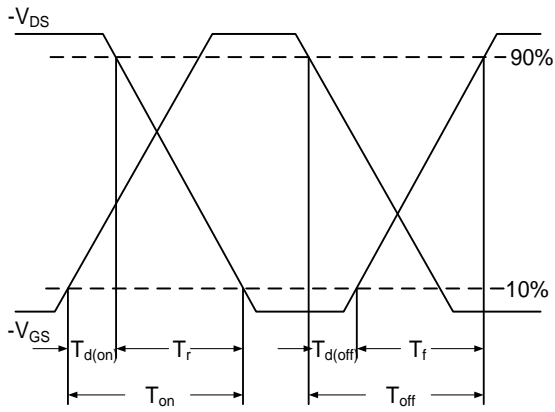
**Fig.4 Gate Charge Waveform**



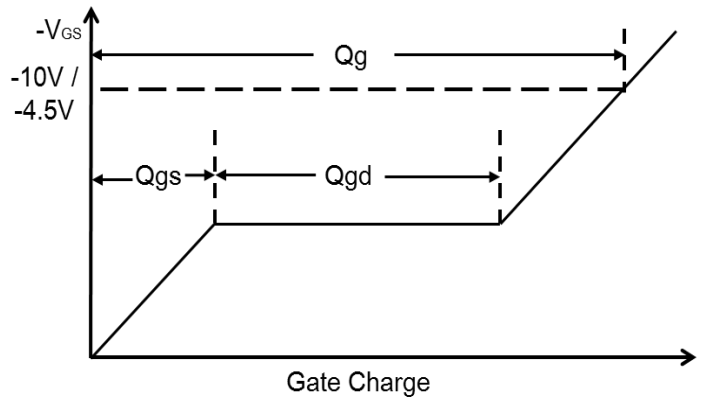
**Fig.5 Normalized Transient Response**



**Fig.6 Maximum Safe Operation Area**

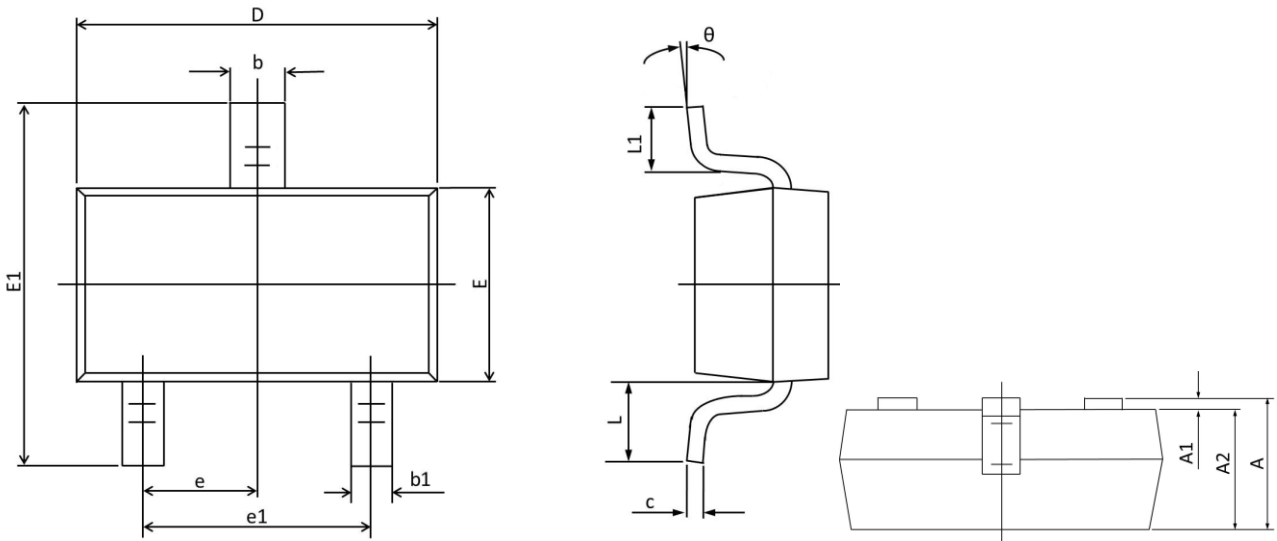


**Fig.7 Switching Time Waveform**



**Fig.8 Gate Charge Waveform**

## SOT523 PACKAGE INFORMATION



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	MAX	MIN	MAX	MIN
A	0.900	0.700	0.035	0.028
A1	0.100	0.000	0.004	0.000
A2	0.800	0.700	0.031	0.028
b	0.350	0.250	0.014	0.010
b1	0.250	0.150	0.010	0.006
c	0.200	0.100	0.008	0.004
D	1.750	1.500	0.069	0.059
E	0.900	0.700	0.035	0.028
E1	1.750	1.400	0.069	0.055
e	0.5TYP.		0.02TYP.	
e1	1.100	0.900	0.043	0.035
L	0.460	0.300	0.018	0.012
L1	0.460	0.260	0.018	0.010
$\theta$	8°	0°	8°	0°